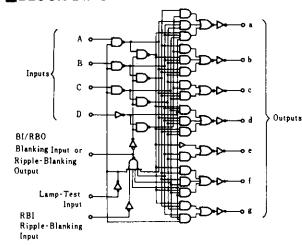
The HD74LS247 is electrically and functionally identical to the HD74LS47, respectively, and has the same pin assignments as its equivalents.

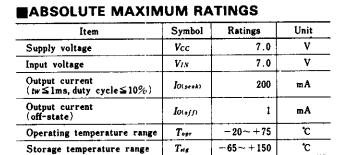
It can be used interchangeably in present or future designs to offer designers a choice between two indicator fonts. The HD74LS47 composes the  $\frac{1}{2}$  and the  $\frac{Q}{2}$  without tails and the HD74LS247 composes the  $\frac{1}{2}$  and the  $\frac{Q}{2}$  with tails. Composition of all other characters, including display patterns for BCD inputs above nine, is identical. The HD74LS247 features active-low outputs designed for driving indicators directly. All of the circuits have full ripple-blanking input/output controls and a lamp test input.

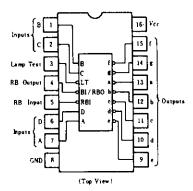
Segment identification and resultant displays are shown below. Display patterns for BCD input counts above 9 are unique symbols to authenticate input conditions. This circuit incorporates automatic leading and/or trailing-edge zero-blanking control (RBI and RBO). Lamp test (LT) of this type may be performed at any time when the BI/RBO node is at a high level. This type contains an overriding blanking input (BI) which can be used to control the lamp intensity be pulsing or to inhibit the outputs.

#### **BLOCK DIAGRAM**



# **■PIN ARRANGEMENT**





#### **MRECOMMENDED OPERATING CONDITIONS**

Item		Symbol	min	typ	max	Unit
Output voltage	a~g	Vo(off)	-	-	15	v
	a~g	IO(on)		-	24	mA
Output current	BI/RBO	Іон	_	_	-50	μA
	BI/RBO	Ιοι	_	_	3.2	mA



#### **EFUNCTION TABLE**

Decimal or	Inputs				BI/RBO Outputs								Note		
Function	LT	RBI	D	С	В	A	→ DI/ NDU	a	ь	c	d	e	f	g	INOLE
0	Н	H	L	L	L	L	Н	ON	ON	ON	ON	ON	ON	OFF	
1	Н	×	L	L	L	Н	H	OFF	ON	ON	OFF	OFF	OFF	OFF	
2	H	×	L	L	Н	L	H	ON	ON	OFF	ON	ON	OFF	ON	
3	Н	×	L	L	Н	Н	Н	ON	ON	ON	ON	OFF	OFF	ON	
4	Н	×	L	Н	L	L	H	OFF	ON	ON	OFF	OFF	ON	ON	
5	Н	×	L	Н	L	Н	Н	ON	OFF	ON	ON	OFF	ON	ON	
6	н	×	L	Н	Н	L	Н	ON	OFF	ON	ON	ON	ON	ON	
7	Н	×	L	Н	Н	Н	Н	ON	ON	ON	OFF	OFF	OFF	OFF	
8	Н	×	Н	L	L	L	Н	ON	ON	ON	ON	ON	ON	ON	1
9	Н	×	Н	L	L	Н	H	ON	ON	ON	ON	OFF	ON	ON	
10	Н	×	Н	L	H	L	H	OFF	OFF	0FF	ON	ON	OFF	ON	
11	Н	×	Н	L	Н	Н	Н	OFF	OFF	ON	ON	OFF	OFF	ON	
12	H	×	Н	Н	L	L	Н	OFF	ON	OFF	OFF	OFF	ON	ON	
13	Н	×	Н	Н	L	Н	Н	ON	OFF	OFF	ON	OFF	ON	ON	
14	Н	×	Н	Н	Н	L	Н	OFF	OFF	OFF	ON	ON	ON	ON	
15	H	×	Н	Н	Н	Н	Н	OFF	OFF	OFF	OFF	OFF	OFF	OFF	
BI	×	×	×	×	×	×	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	2
RBI	Н	L	L.	L	L.	L	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	3
LT	L	×	×	×	×	×	н	ON	ON	ON	ON	ON	ON	ON	4

H; high level, L; low level, X; irrelevant

- Notes)
  1. The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired.

  The ripple-blanking input (RBI) must be open or high if blanking of a decimal zero is not desired.
  - When a low logic level is applied directly to the blanking input (BI), all segment outputs are off regardless of the level of any other input.
- When ripple-blanking input (RBI) and inputs A, B C, and D are a low level with the lamp test input high, all segment outputs go off and the ripple-blanking output (RBO) goes to a low level (response condition).
- When a blanking input ripple blanking input (BI/RBO) is open or held high and a low is applied to the lamp-test input, all segment outputs are on.

# **TELECTRICAL CHARACTERISTICS** ( $Ta = -20 \sim +75$ °C )

Item		Symbol	Test Condition	ons	min	typ *	max	Unit
Input voltage		ViH		2.0	-	-	V	
		VIL	VIL				0.8	V
BI/RBO		Von	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8$	V, Ion = -50μ A	2.4		-	V
Output voltage			$V_{CC} = 4.75 \text{V}, V_{IH} = 2 \text{V}$	IoL = 1.6mA	-	· · · · · · · · · · · · · · · · · · ·	0.4	v
	BI/RBO	Vot	$V_{IL}=0.8V$	IoL = 3.2mA		-	0.5	V
Output current	a∼g	Io(off)	$V_{CC} = 5.25V$ , $V_{IH} = 2V$ , $V_{IL} = 0.8V$ , $V_{O(*ff)} = 15V$		-		250	μA
Output voltage	a∼g	VO(on)	$V_{CC}=5.25$ V, $V_{IH}=2$ V	$I_{O(on)} = 12 \text{mA}$	-	-	0.4	0.4 V
			$V_{IL}=0.8V$	IO(on) = 24mA			0.5	V
	·L	Iн	$V_{CC} = 5.25 \text{V},  V_I = 2.7 \text{V}$			20	μА	
_	except BI/RBO					_	- 0.4	m A
Input current	BI/RBO	Tr L	$V_{CC} = 5.25 \text{V},  V_I = 0.4 \text{V}$	ľ	_	<del>-</del>	-1.2	mA
\		Iı .	$V_{CC} = 5.25 \text{V},  V_I = 7 \text{V}$		-		0.1	mΑ
Short-circuit	Bl/RBO	Ios	$V_{CC} = 5.25 \text{V}$		0.3	-	-2	m A
Supply current **		<b>I</b> cc	$V_{CC} = 5.25 \text{V}$		-	7	13	mΑ
Input clamp voltage		Vik	$V_{CC} = 4.75 \text{V},  I_{IN} = -18 \text{mA}$				1.5	V

<sup>•</sup> VCC=5V, Ta=25°C

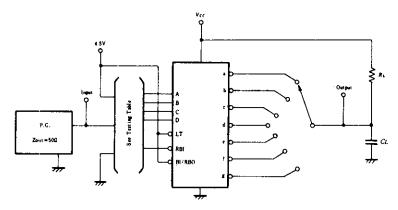
<sup>\*\*</sup> ICC is measured with all outputs open and all inputs at 4.5V.

# **ESWITCHING CHARACTERISTICS** ( $V_{CC} = 5V$ , $T_a = 25^{\circ}C$ )

Item	Symbol	Input	Test Conditions	min	typ	max	Unit
Turn-on time		A			—	100	
turn-on time	ton	RBI	$C_L=15 \mathrm{pF}, R_L=665 \Omega$	_	_	100	ns
Turn-off time	toff	A			_	100	
Turn-on time		RBI		_	-	100	ns

### **TESTING METHOD**

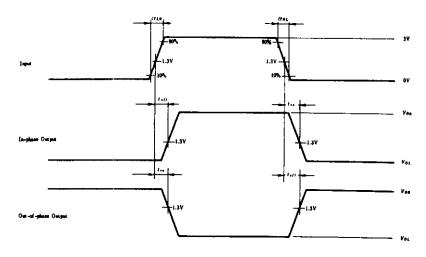
#### 1) Test Circuit



#### 2) Testing Table

Ta		Inputs						Outputs						
Item	RBI	D	С	В	A	a	ь	С	d	е	f	g		
	4.5V	GND	GND	GND	IN	OUT		_	OUT	OUT	OUT	_		
lon	4.5V	GND	GND	4.5V	IN	_	_	OUT		TUO	<del></del>			
toff	4.5V	GND	4.57	4.5V	IN	-	OUT		OUT	OUT	OUT	OUT		
	IN	GND	GND	GND	GND	OUT	OUT	OUT	OUT	OUT	OUT			

#### Waveform

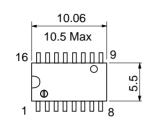


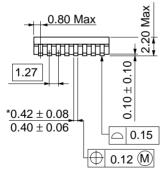
Notes) i. Input pulse:  $t_{TLH} \le 15$ ns,  $t_{THL} \le 6$ ns, PRR = 1MHz, duty cycle=50%.

2. C<sub>L</sub> includes probe and jig capacitance.

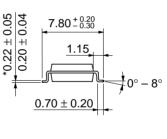
Unit: mm 19.20 20.00 Max 16 7.40 Max 6.30 1.3 1.11 Max 7.62 5.06 Max 2.54 Min 0.51 Min  $0.25^{+0.13}_{-0.05}$  $0.48 \pm 0.10$  $2.54\pm0.25$  $0^{\circ} - 15^{\circ}$ Hitachi Code DP-16 **JEDEC** Conforms EIAJ Conforms Weight (reference value) 1.07 g

Unit: mm





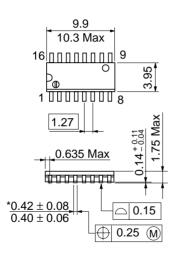


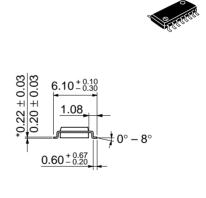


Hitachi Code	FP-16DA
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.24 g

\*Dimension including the plating thickness
Base material dimension

Unit: mm





\*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

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